



NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE NOT METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. DIE ATTACH PAD IS ELECTRICALLY CONNECTED TO PIN NO.3.
5. LEAD RESISTANCE: 0.10Ω MAX.

SSM P/N LCC00603

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|-----------------------|---------|----------|-------------|------------|
| EB000Z895-1 | | | | S=N D=3 |
| DRAWN | CHECKED | APPROVED | DATE | |
| S. SH | K.K K.M | M.K | NOV.14, '91 | |
| DRAWING NO. KD-E91895 | | | | SHEET 1/1 |

| | | | | |
|---------|---------------------|--------------|-----------|----------------------------|
| NAME | 6 LEAD CHIP CARRIER | | TOLERANCE | UNLESS OTHERWISE SPECIFIED |
| SCALE | 10 / 1 | MATERIAL | ±.005 | TURBO ABLE PROJECTION |
| | | AS INDICATED | | |
| CHANGED | | DATE | DRAWN | CHECKED |
| | | | | APPROVED |



KYOCERA CORPORATION
KYOTO JAPAN